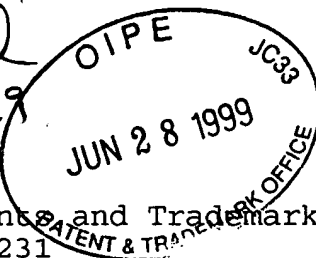


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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/310,256 05/12/99

S.J. Chin, S.J. Linc

A METHOD TO REDUCE PARTICLE LEVEL
FOR DRY-ETCH

Grp. Art Unit: ~~1753~~

1746

INFORMATION DISCLOSURE STATEMENT

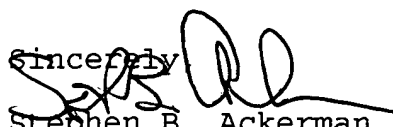
Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,215,619 to Cheng et al., "Magnetic Field-
Enhanced Plasma Etch Reactor", shows a plasma reactor with a
cleaning operation.

U.S. Patent 4,786,392 to Kruchowski et al., "Fixture for
Cleaning a Plasma Etcher", shows a fixture for cleaning a
plasma etcher.

Sincerely,


Stephen B. Ackerman,
Reg. No. 37661